WE CLAIM:

1. Process for manufacturing a laser, characterized in that it comprises the following operations:

   - deposition of layers designed to form said stack (12);
   - deposition of a masking layer (14);
   - etching of the masking layer (14) outside of the zone designed to form said stack;
   - etching of the layers designed to form the stack (12) outside of the masked zone;
   - metal organic chemical vapour deposition (MOCVD) of an electrically insulating layer (22) on the non-masked parts, until a thickness substantially equal to the thickness of the stack (12) is reached;
   - removal of the masking layer (14), and
   - deposition of a conducting layer (24), covering in particular the stack (12) on its upper surface.

2. Process according to claim 1, characterized in that the operation of deposition of the electrically insulating layer (22) is performed until a thickness substantially equal to the thickness of the stack (12) is reached.

3. Process according to claim 1, characterized in that said masking layer (14) is manufactured in SiO_2.

4. Process according to claim 2, characterized in that said masking layer (14) is manufactured in SiO_2.